

ABSTRACT

A wire bond pad and method of fabricating the wire bond pad. The method including: providing a substrate; forming an electrically conductive layer on a top surface of the substrate; patterning the conductive layer into a plurality of wire bond pads spaced apart; and forming a protective dielectric layer on the top surface of the substrate in spaces between adjacent wire bond pads, top surfaces of the dielectric layer in the spaces coplanar with coplanar top surfaces of the wire bond pads.